

STARPOWER

SEMICONDUCTOR

IGBT

GD200HFT120C5S_G8

1200V/200A 2 in one-package

General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as general inverter and UPS.

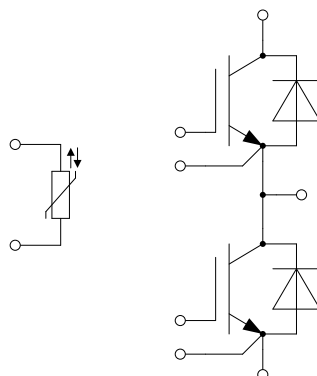
Features

- Low $V_{CE(sat)}$ Trench IGBT technology
- 10 μ s short circuit capability
- $V_{CE(sat)}$ with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper baseplate using DBC technology

Typical Applications

- Inverter for motor drive
- AC and DC servo drive amplifier
- Uninterruptible power supply

Equivalent Circuit Schematic



Absolute Maximum Ratings $T_C=25^{\circ}\text{C}$ unless otherwise noted**IGBT**

Symbol	Description	Value	Unit
V_{CES}	Collector-Emitter Voltage	1200	V
V_{GES}	Gate-Emitter Voltage	± 30	V
I_C	Collector Current @ $T_C=25^{\circ}\text{C}$	310	A
	@ $T_C=100^{\circ}\text{C}$	200	
I_{CM}	Pulsed Collector Current $t_p=1\text{ms}$	400	A
P_D	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	1034	W

Diode

Symbol	Description	Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V
I_F	Diode Continuous Forward Current	200	A
I_{FM}	Diode Maximum Forward Current $t_p=1\text{ms}$	400	A

Module

Symbol	Description	Value	Unit
T_{jmax}	Maximum Junction Temperature	175	$^{\circ}\text{C}$
T_{jop}	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
T_{STG}	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
V_{ISO}	Isolation Voltage RMS, $f=50\text{Hz}$, $t=1\text{min}$	2500	V

IGBT Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=200\text{A}, V_{GE}=15\text{V}, T_j=25^\circ\text{C}$		1.70	2.15	V	
		$I_C=200\text{A}, V_{GE}=15\text{V}, T_j=125^\circ\text{C}$		1.95			
		$I_C=200\text{A}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}$		2.00			
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=8.0\text{mA}, V_{CE}=V_{GE}, T_j=25^\circ\text{C}$	5.0	5.8	6.5	V	
I_{CES}	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$			5.0	mA	
I_{GES}	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^\circ\text{C}$			400	nA	
R_{Gint}	Internal Gate Resistance			1.0		Ω	
C_{ies}	Input Capacitance	$V_{CE}=30\text{V}, f=1\text{MHz}, V_{GE}=0\text{V}$		18.2		nF	
C_{res}	Reverse Transfer Capacitance			0.56		nF	
Q_G	Gate Charge	$V_{GE}=15\text{V}$		1.20		μC	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=200\text{A}, R_G=3.0\Omega, V_{GE}=\pm 15\text{V}, T_j=25^\circ\text{C}$		213		ns	
t_r	Rise Time			64		ns	
$t_{d(off)}$	Turn-Off Delay Time			280		ns	
t_f	Fall Time			180		ns	
E_{on}	Turn-On Switching Loss			4.10		mJ	
E_{off}	Turn-Off Switching Loss			16.3		mJ	
$t_{d(on)}$	Turn-On Delay Time		$V_{CC}=600\text{V}, I_C=200\text{A}, R_G=3.0\Omega, V_{GE}=\pm 15\text{V}, T_j=125^\circ\text{C}$		285		ns
t_r	Rise Time				78		ns
$t_{d(off)}$	Turn-Off Delay Time			363		ns	
t_f	Fall Time			278		ns	
E_{on}	Turn-On Switching Loss			7.40		mJ	
E_{off}	Turn-Off Switching Loss			23.0		mJ	
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=600\text{V}, I_C=200\text{A}, R_G=3.0\Omega, V_{GE}=\pm 15\text{V}, T_j=150^\circ\text{C}$			293		ns
t_r	Rise Time				81		ns
$t_{d(off)}$	Turn-Off Delay Time			374		ns	
t_f	Fall Time			327		ns	
E_{on}	Turn-On Switching Loss			8.70		mJ	
E_{off}	Turn-Off Switching Loss			25.2		mJ	
I_{SC}	SC Data		$t_p \leq 10\mu\text{s}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}, V_{CC}=900\text{V}, V_{CEM} \leq 1200\text{V}$		800		A

Diode Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
V_F	Diode Forward Voltage	$I_F=200\text{A}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$		1.70	2.15	V
		$I_F=200\text{A}, V_{GE}=0\text{V}, T_j=125^\circ\text{C}$		1.65		
		$I_F=200\text{A}, V_{GE}=0\text{V}, T_j=150^\circ\text{C}$		1.65		
Q_r	Recovered Charge			17.5		μC
I_{RM}	Peak Reverse Recovery Current	$V_{CC}=600\text{V}, I_F=200\text{A},$ $-di/dt=5500\text{A}/\mu\text{s}, V_{GE}=-15\text{V},$ $T_j=25^\circ\text{C}$		245		A
E_{rec}	Reverse Recovery Energy			8.00		mJ
Q_r	Recovered Charge			32.0		μC
I_{RM}	Peak Reverse Recovery Current	$V_{CC}=600\text{V}, I_F=200\text{A},$ $-di/dt=5500\text{A}/\mu\text{s}, V_{GE}=-15\text{V},$ $T_j=125^\circ\text{C}$		260		A
E_{rec}	Reverse Recovery Energy			14.0		mJ
Q_r	Recovered Charge			37.5		μC
I_{RM}	Peak Reverse Recovery Current	$V_{CC}=600\text{V}, I_F=200\text{A},$ $-di/dt=5500\text{A}/\mu\text{s}, V_{GE}=-15\text{V},$ $T_j=150^\circ\text{C}$		265		A
E_{rec}	Reverse Recovery Energy			15.3		mJ

NTC Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
R_{25}	Rated Resistance			5.0		$\text{k}\Omega$
$\Delta R/R$	Deviation of R_{100}	$T_c=100^\circ\text{C}, R_{100}=493.3\Omega$	-5		5	%
P_{25}	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K

Module Characteristics $T_c=25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
L_{CE}	Stray Inductance		30		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip		2.20		$\text{m}\Omega$
R_{thJC}	Junction-to-Case (per IGBT)			0.145	K/W
	Junction-to-Case (per Diode)			0.243	
R_{thCH}	Case-to-Heatsink (per IGBT)		0.064		K/W
	Case-to-Heatsink (per Diode)		0.107		
	Case-to-Heatsink (per Module)		0.02		
M	Terminal Connection Torque, Screw M6	3.0		6.0	N.m
	Mounting Torque, Screw M5	2.5		5.0	
G	Weight of Module		200		g

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